

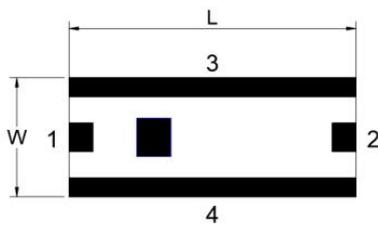
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

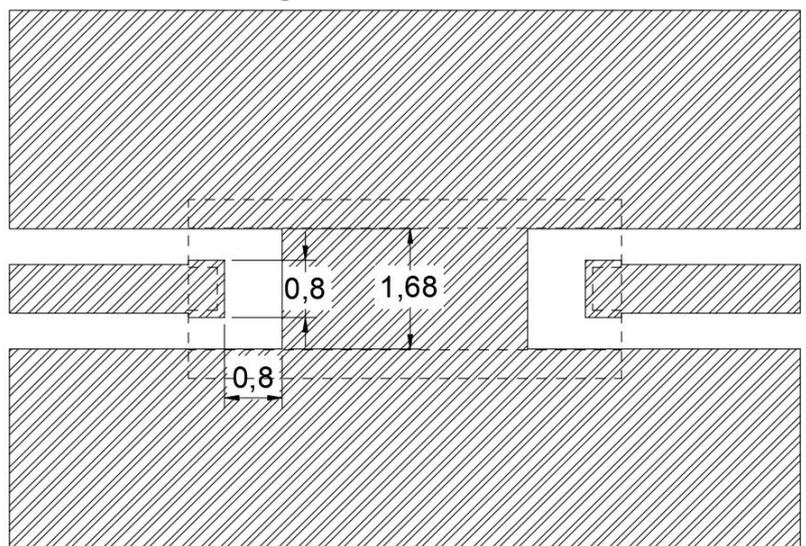
NO.	Parameter	SPEC	
1	Frequency (MHz)	5850~6200	
2	Insertion Loss (dB) @25°C	≤3.0	
3	VSWR(In BW)	≤2.5	
4	Attenuation(dB)	5300MHz	≥35
		6700MHz	≥20
5	In/Output Impedance (Ω)	50	
6	Power	5W	
<b>Operating &amp; Storage Condition (Component)</b> Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C~ +85°C <b>Storage Condition before Soldering (Included packaging material)</b> Storage Temperature Range: +5 ~ +40 °C Humidity: 30 to 70% relative humidity			

### Construction



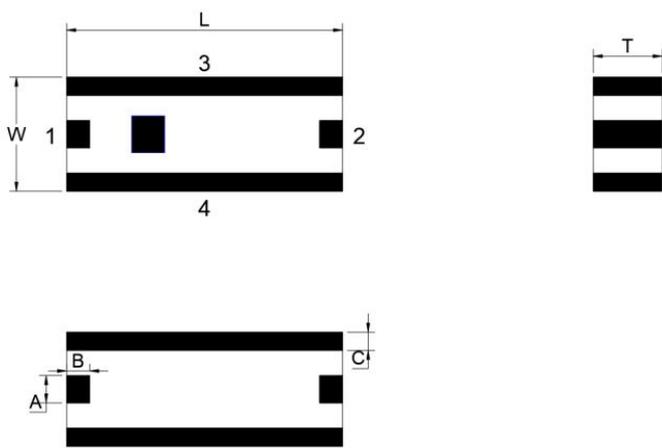
PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

### Mounting Considerations

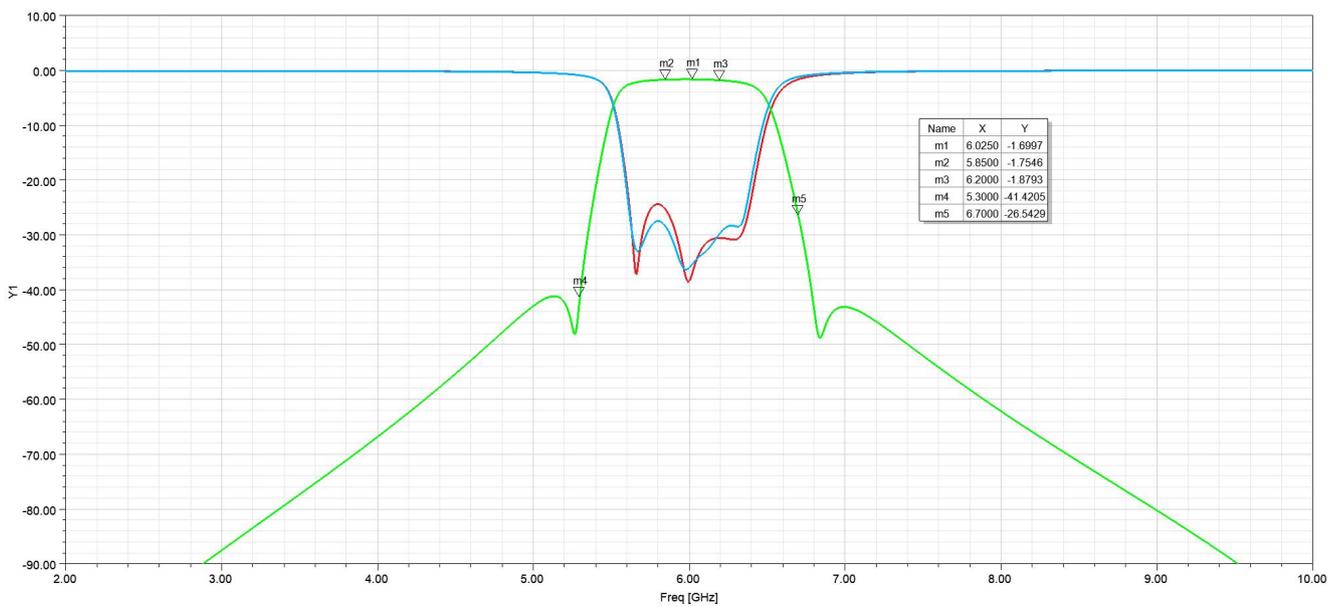


Unit: mm

### Dimensions

Figure	Symbol	Dimension (mm)
	L	6.00 ± 0.20
	W	2.50 ± 0.20
	T	2.00MAX
	A	0.60± 0.10
	B	0.40 ± 0.10
	C	0.40± 0.10

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.